

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	128	Metal with bump with die	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:54
2	BRS	L2	0	1 and (bump with bind\$3 with finger with leadframe)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:57
3	BRS	L3	0	bump with bind\$3 with finger with leadframe	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:18
4	BRS	L4	0	bind\$3 with finger with leadframe	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:19
5	BRS	L5	133	finger with leadframe	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:58
6	BRS	L6	0	1 and 5	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:19

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	3	5 and (heat\$3 near3 bump)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:21
8	BRS	L8	5484	Metal with bump	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:55
9	BRS	L9	0	8 and (bump with bind\$3 with finger with leadframe)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:57
10	BRS	L10	0	8 and (bind\$3 with finger with leadframe)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:58
11	BRS	L11	3	8 and (finger with leadframe)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 10:00
12	BRS	L12	3	11 and heat\$3	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 10:01

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L13	1	11 and press\$3	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 12:07
14	IS&R	L14	2	("5252853").PN.	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:46
15	BRS	L15	14	flip with leadframe with package	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:50
16	BRS	L16	3	15 and heat\$3 and press\$3	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:54
17	BRS	L17	1	16 and bump	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:53
18	BRS	L18	614685	flip chip interconnection	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:53

	Type	L #	Hits	Search Text	DBs	Time Stamp
19	BRS	L19	733	flip with chip with interconnection	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:53
20	BRS	L20	315	19 and heat\$3 and press\$3	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:54
21	BRS	L21	184	19 and heat\$3 and press\$3 and bump	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:55
22	BRS	L22	83	21 and (temperature same pressure)	USPAT ; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:55